Sreejith Kochupurackal Rajan

List of Publications by Year
in descending order

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14	58	4	6
papers	citations	h-index	g-index

1937685 1872680

15	15	15	33
all docs	docs citations	times ranked	citing authors

#	Article	IF	Citations
1	BEOL-Embedded 3D Polylithic Integration: Thermal and Interconnection Considerations. , 2020, , .		12
2	Microfluidic Cooling of a 14-nm 2.5-D FPGA With 3-D Printed Manifolds for High-Density Computing: Design Considerations, Fabrication, and Electrical Characterization. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2019, 9, 2393-2403.	2.5	8
3	Integrated Silicon Microfluidic Cooling of a High-Power Overclocked CPU for Efficient Thermal Management. IEEE Access, 2022, 10, 59259-59269.	4.2	7
4	Monolithic Microfluidic Cooling of a Heterogeneous 2.5-D FPGA With Low-Profile 3-D Printed Manifolds. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2021, 11, 974-982.	2.5	6
5	Microfabrication, Coil Characterization, and Hermetic Packaging of Millimeter-Sized Free-Floating Neural Probes. IEEE Sensors Journal, 2021, 21, 13837-13848.	4.7	5
6	Polylithic Integration for RF/MM-Wave Chiplets using Stitch-Chips: Modeling, Fabrication, and Characterization. , 2020, , .		4
7	Polylithic Integration of 2.5-D and 3-D Chiplets Enabled by Multi-Height and Fine-Pitch CMIs. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2020, 10, 1474-1481.	2.5	4
8	A Substrate-Agnostic, Submicrometer PSAS-to-PSAS Self-Alignment Technology for Heterogeneous Integration. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2021, 11, 2061-2068.	2.5	4
9	Design Considerations, Demonstration, and Benchmarking of Silicon Microcold Plate and Monolithic Microfluidic Cooling for 2.5D ICs. , 2021, , .		3
10	Electrical Characterization and Benchmarking of Polylithic Integration Using Fused-Silica Stitch-Chips With Compressible Microinterconnects for RF/mm-Wave Applications. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2021, 11, 1824-1834.	2.5	3
11	A Die-Level, Replaceable Integrated Chiplet (PINCH) Assembly Using a Socketed Platform, Compressible MicroInterconnects, and Self-Alignment. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2021, 11, 2069-2076.	2.5	2
12	Reading bits on a CDâ€ROM without a photodiode. IET Optoelectronics, 2017, 11, 213-216.	3.3	0
13	High Density and Low-Temperature Interconnection Enabled by Mechanical Self-Alignment and Electroless Plating. , 2019, , .		0
14	Electrical and Performance Benefits of Advanced Monolithic Cooling for 2.5D Heterogeneous ICs. , 2021, , .		0